

ESTC 2008

2nd Electronics System-Integration Technology Conference
1st – 4th September 2008, Greenwich, London, UK

www.estc.biz

The IEEE 2nd ESTC **Electronics Systems-Integration Technology Conference** is on track to be an outstanding technical event and exhibition. ESTC-2008 will comprise 270 themed technical papers in six parallel oral tracks and posters. Posters will be displayed and also be presented.

The Technical themes at ESTC-2008 are:

- Advanced Packaging
- Emerging Technologies
- Manufacturing and Test Technology
- Modelling, Simulation and Design
- New Materials and Processes
- Power Electronics
- Technology & Reliability for Micro and Nano Systems
- Assembly of Alternative Energy Sources
- Optoelectronics
- Electronics system-integration for healthcare.

Special invited Sessions:

Asia-Pacific Photo-voltaics will address: • “Third Generation Photo-voltaics” • “System-integration Strategies for co-Generation of Electricity, Heating and Cooling using Solar Photo-voltaic Modules” • “Building Integrated Photo-voltaics for Maximum Power Generation” • “The Intellectual Property Landscape for Photovoltaic Technologies”

Standards will address: “The Critical Standards for BT’s 21st Century Network” • “EMC and Functional Safety Requirements for Integrated Electronics Systems” • “The Evolution of Standards in Industry”

Prognostics and System Health Management for Reliability will address: “Embedded Prognostics and Health Monitoring Systems” • “Integrated Vehicle Health Management in the Auto Industry” • “Aerospace and Electronics System Prognostic Health Management” • “Detecting Anomalies in Field Returned Laptops using Mahalanobis Distance”

Greening the Blue Planet (public session): • “Electronics, Energy and the Environment” Johns Hopkins University • “Interdependence of Marine Ecosystems and Climate Change” WWF • “Future Parks in Future Climates - scalable solutions” Ecologist Brecon National Park • “Talking Green about Nuclear” University of Cardiff

Short Courses

Eight half-day short courses will be taught on Monday 1st September

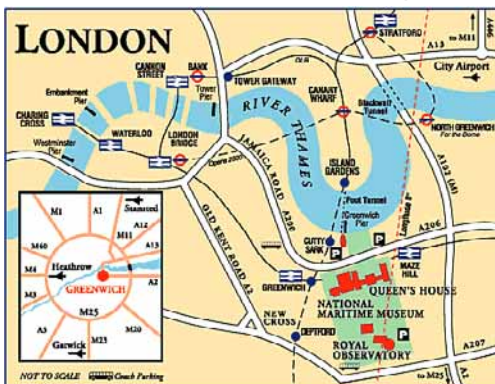
Opening and Keynotes

The Conference will be opened on Tuesday 1st September by Baroness Blackstone, Chancellor of the University of Greenwich. The Keynote Opening Address will be on “**Ambient Assisted Living**” by Dr. Nakita Vodjdani, Vice-President of the European Union AAL Association. The Keynote closing address will be by Prof. Peter Cochrane, entrepreneur and former Chief Technologist of British Telecom

Attendance is expected to exceed 500 international delegates.

The major technical exhibition will be held alongside the Conference – an excellent opportunity for suppliers of materials, design houses, circuit manufacturers to promote their products and reach potential customers.

ESTC 2008 will be held at Greenwich, a World heritage site and major maritime site on the banks of the River Thames in the magnificent city that is London. The Conference and Exhibition will be hosted by the University of Greenwich in the buildings of the former Royal Naval College. Plenary sessions will be in the Great Painted Hall – providing a wonderful ambience for the technical presentations.



Visit: www.estc.biz

Information: sinnadurai@estc.biz

2nd International Conference on

Thermal issues in Emerging Technologies, Theory and Applications

ThETA2 Cairo, Egypt, December 17th – 20th, 2008

The ThETA conference objective is to address the growing impact of thermal issues on most of the advanced technologies including Microelectronics, Nanotechnology, Smart Materials, Micro-Electro-Mechanical Systems, Biomedical engineering, New Energies, Two-phase flow, and more.

Parallel to the conference, a set of workshops will be conducted, aiming at disseminating advances made in different areas to the academic and industrial public in Egypt, fostering network creation with renowned international research centers as well as giving an impulse to academic/industrial cooperation.

DEADLINES

Submitting abstracts: **June 2nd 2008**
Notification of abstract acceptance: **June 16th 2008**
Submitting full papers: **Sep. 8th 2008**
Notification of paper acceptance: **Oct. 6th 2008**
Camera Ready full paper: **Nov. 3rd 2008**

Abstracts size: ~1000 words. Required data: Paper title, author(s) name(s) and affiliation(s), contact author email.

File formats: .txt, .doc, .pdf, .xsw

Send to thetaconf@gmail.com

CALL FOR PAPERS

Topical Areas:

- * Thermal modeling of electronic systems
- * Temperature aware computer systems design
- * Cooling of electronic systems and data centers
- * Micro and Nano scale heat transfer
- * Modeling of multiple scale heat transfer problems
- * Compact thermal models
- * Thermo-mechanical analysis in electronic systems
- * MEMS – multiphysical problems
- * Computational methods in heat transfer
- * Energy conservation
- * Fuel cells
- * Solid state energy generation / cooling
- * Multiphase flow with heat transfer
- * Thermal issues in biomedical engineering (diagnosis – therapy)
- * Thermal Issues in Microfabrication Technology
- * Thermal issues in new materials
- * New experimental methods in heat transfer

For full CFP and further information:

www.thetaconf.org

ABSTRACT SUBMISSION DEADLINE EXTENDED TO JUNE 15TH.

33RD INTERNATIONAL ELECTRONICS MANUFACTURING TECHNOLOGY CONFERENCE IEMT 2008

4th-6th November, 2008

Parkroyal Hotel, Penang, MALAYSIA

ABOUT IEMT

The 33rd International Electronics Manufacturing Technology Conference (IEMT 2008) is an international event organized by the IEEE CPMT Malaysia Chapter with co-sponsorship from CPMT Santa Clara Chapter. IEMT 2008 will feature short courses, technical sessions, and exhibitions. It aims to provide good coverage of technological developments in all areas of electronics packaging, from design to manufacturing and operation. IEMT 2008 is an international forum, providing opportunities to network and meet leading experts. Since the 1980's, IEMT has gained a reputation as a premier electronics materials and packaging conference and is well attended by experts in the field of electronic packaging and manufacturing from all over the world.

IEMT 2008 will feature short courses, technical sessions, and exhibitions. It aims to provide good coverage of technological developments in all areas of electronics packaging, from design to manufacturing and operation.

CONFERENCE TOPICS

The topics of interests are specific to electronics packaging, electronics materials, electronics manufacturing technology and reliability issues. Extended abstracts are being sought from, but not limited to, the following areas:

- Emerging Packaging Technologies
- Advanced Packaging
- Interconnection Technologies
- Manufacturing Technologies
- Surface Mount Technology
- IC Testing Technology
- Materials & Processes
- MEMS Packaging
- Electrical Modeling & Signal Integrity
- Thermal Characterization & Cooling Solutions
- Mechanical Modeling & Structural Integrity
- Quality and Reliability
- Chip-Scale Packaging/Flip Chip
- Wafer Fabrication Manufacturing

ABSTRACT AND PAPER SUBMISSION

Send 500 words stating clearly the purpose, methodology, results, and conclusions of the work, by **15 JUNE 2008**. Further information on the website:

cpmt.ieeemalaysia.org

EPTC 2008

10th Electronics Packaging Technology Conference
9th – 12th Dec 2008, Grand Copthorne Waterfront Hotel, Singapore.

10th Year Anniversary
Celebration!

CALL FOR PAPERS

BIGGER Event!
4 Days Conference

ABOUT EPTC

The 10th Electronics Packaging Technology Conference (EPTC 2008) is an International event organized by the IEEE Reliability/CPMT/ED Singapore Chapter, sponsored by IEEE CPMT Society.

EPTC 2008 is a 4-day event in conjunction with 10th year conference anniversary celebration. It will feature technical sessions, short courses/forums, exhibition, social and networking activities. It aims to provide a good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in Asia and is well attended by experts in all aspects related to packaging technology from all over the world.

CONFERENCE TOPICS

You are invited to submit an abstract, presenting new development in the following categories:

- **Advanced Packaging & Emerging Technologies:** *Wafer level packaging, 3D integration, embedded passives & actives on substrates, high power modules, high pin count flip chip packaging, RF-ID, SiP and other system integration technologies. Packaging solutions for MEMS, Bio-electronics, Automotive electronics, optoelectronics, organic and printable electronics.*
- **Interconnection Technologies:** *Gold and copper wire bonding and flip chip (eutectic/lead-free solders) on standard and copper low-k wafers, solder replacement flip chip (ICP, ACP, ACF, NCP), under bump metallurgy, 3D and through Si via connections, microvia and build-up technologies, fine pitch interconnects, nano interconnects.*
- **Manufacturing Technologies:** *Sustainable volume production of advanced packages and emerging technologies. New manufacturing technologies focusing on incorporating rapid product changes, cost, yield improvement, electrical/mechanical and environmental performance.*
- **Materials & Processes:** *Advancements in adhesives, encapsulants, underfills, solder alloys, ROHS compliant materials, flexible dielectrics, ceramics, composites, thin film processes on laminates, nano-materials and assembly processes, advanced material characterization techniques.*
- **Electrical Modeling & Signal Integrity:** *Modeling simulation & measurement for coupling, signal Integrity, power integrity & decoupling scheme analysis reflection, switching noise, EMI/EMC analysis on package & subsystems, RF modules, time & frequency domain measurements for advanced modules.*

- **Thermal Characterization & Cooling Solutions:** *Modeling & simulation methodology for thermal characterization of advanced packaging, modules & systems. Novel thermal management solutions. Enhanced air & liquid cooling techniques, Hot-spot management.*
- **Mechanical Modeling & Structural Integrity:** *Thermo-mechanical modeling at package, board & system levels. Modeling of delamination, moisture diffusion, hygrostress, thermal cycling, drop impact, bend, vibration, solder joint reliability and life prediction, measurement of material & interface properties, experimental verification.*
- **Quality & Reliability:** *Component, board and system level reliability assessment, interfacial adhesion, accelerated testing and models, advances in reliability test methods and failure analysis.*

Important Dates

10th June 2008

30th June 2008

30th August 2008

Submission of abstract

Notification of Acceptance

Submission of manuscript

Abstract and Paper Submission

Abstracts are solicited to describe original and unpublished work. The abstract should be at least 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well.

Authors must designate two appropriate categories for abstract review. All submissions must be in English and should be made via the online submission system found at <http://www.eptc-ieee.net>. The required file format is Adobe Acrobat® PDF or MS Word in one single file for each submission.

The abstracts must be received by **10th June 2008**. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Special gift (webcam) will be given to the first 20 submitted abstracts which are subsequently accepted and published. Authors will be notified of paper acceptance and publication instruction by 30th June 2008. The final manuscript for publication in the conference proceedings is due by 30th August 2008. Selected papers will be published in IEEE/CPMT journals.

Outstanding Technical Papers

The conference proceedings is an official IEEE publication. Author(s) of Outstanding Technical Paper(s) and Best Student Paper will receive an award at the next conference.

Call for Short Courses

The conference program includes half and full-day short courses which will be conducted by leading experts in the field. Details will be updated in the conference website and available in subsequent mailings. Proposals for short courses can be submitted to techchair@eptc-ieee.net.

Call for Exhibition / Sponsorship

A tabletop exhibition featuring suppliers of materials, equipment, components, software and service providers of the microelectronics and electronic assembly industries will be held during the conference. Potential exhibitors and sponsors may email secretariat@eptc-ieee.net for details.

Organized by



IEEE Reliability/CPMT/ED Singapore Chapter

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Sponsored by



IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

Conference information & contacts:

Website: <http://www.eptc-ieee.net>

Email: secretariat@eptc-ieee.net

Call for Papers

9th VLSI PACKAGING WORKSHOP in JAPAN (VPWJ) Dec. 1 - 2, 2008 Kyoto, Japan

Bring your latest research results and share with the participants who are experts from industry and academia, and discuss with them.. The following areas of technology are of primary interest to the participants:

- System in a Package (SiP) - MEMS Packaging Technologies
- Advanced Fine Pitch Packaging
- Nano-Technology
- 3D Packaging & COC (Chip on Chip)
- Micro Bumping Technology
- Wafer Level CSP
- Electrical Performance & Thermal Management
- Packaging for Optoelectronics
- Failure Mechanisms & Reliability Improvement
- Packaging for Automobiles
- Materials for High Speed Application & Wafer Processing
- RF Components & Modules/RF Tags
- Green Materials
- Integrated Passives/Embedded Components
- Assembly and Packaging Challenges for Cu/Low-k Chips
- Laminated Materials & Processing
- Emerging Technologies

Those who wish to contribute to the workshop should send a two-page abstract of a paper (including figures) to the Program Chair, Hiroshi Yamada at Toshiba, by **May 31, 2008**.

For full Call for Papers, see:

vlsi-pkg-ws.org

Workshop on Accelerated Stress Testing & Reliability

October 29-31, 2008 Portland Oregon

Theme: "Achieving Cradle to Grave Reliability using DFR and AST"

The ASTR Workshop is an annual CPMT gathering of test and reliability engineers focused on accelerated stress testing and its relationship to reliability. It provides a forum for people from many different disciplines to network and discuss related issues and methodologies. Over the last few years, Accelerated Stress Testing & Reliability (ASTR) has been embraced by an ever widening array of worldwide companies seeking to reconcile the need for the highest quality product with the necessary push for early time-to-market.

Completed Presentation Deadline: June 13, 2008

Registration is now open – save through Sept. 30th.

Please visit:

www.ewh.ieee.org/soc/cpmt/tc7/ast2008

Polytronic '08



7th International IEEE Conference on Polymers and Adhesives in Microelectronics and Photonics

Garmish-Partenkirchen, Germany 17-22 August, 2008

Please join researchers, engineers and scientists from around the world in mid-August 2008 to share knowledge and experience in Polymeric Materials for Microelectronic & Photonic Applications (POLY), Adhesives in Electronics, and Polymeric Electronics Packaging (PEP). The program will include keynote, invited and contributed presentations, as well as panel discussions. There are eight half-day tutorials and an IEEE Pavilion featuring technology exhibits and demonstrations.

For the Program and registration details, visit:

www.polytronic2008.com

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Visit ieeexplore.ieee.org and download them

Purchase the CD-ROM at

www.cpmt.org/proceedings

IMPACT 2008:

3rd International Microsystems, Packaging, Assembly and Circuits Technology

October 22 to 24, 2008

“Creative Collaboration, More Than Packaging”

Call for Papers

Microsystems & Packaging Technology

- Advanced Packaging Technology - Assembly & Manufacturing - Modeling, Testing & Design
- Advanced Microsystems Technology - Materials, Process & Equipment - Emerging Technology

Materials and Packaging

- Materials and Processing - Passive and Active Components - Optoelectronics/Photonics - Sensor, Actuator, and Transducer Technologies - Quality and Reliability - Advanced Packaging - Thru Silicon Via (TSV) Technology - Interconnection Technologies - System-in-Package (SiP) and 3D Stacked Die Packaging - Electrical Modeling, Characterization, and Signal Integrity - Thermal-Mechanical Modeling and Characterization - Packaging Technologies for High Brightness LEDs - Flexible Electronics

EMAP 2008:

10th International Conference on Electronics Materials and Packaging

Taipei Nangang Exhibition Hall

Joint IMPACT-EMAP Conference

Electronic Circuits Technology (PCBs)

- Material & Processes - Equipment & Processes
- Manufacturing Technology - Test & Inspection Technology - General Topics - Emerging Technology

The 400-500 word abstract should be submitted electronically through the conference website by **May 31, 2008**. Full paper is to be submitted electronically by August 31.

Visit: www.impact-emap.org

Plan to attend and participate!

IEEE Components, Packaging and Manufacturing Technology Society

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